

Global IC Bonder Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global IC Bonder market size was valued at US\$ 954 million in 2025 and is forecast to a readjusted size of US\$ 1409 million by 2032 with a CAGR of 5.7% during review period.

IC Bonder, commonly referred to as Die Bonder or Die Attach Equipment, is a type of semiconductor assembly equipment used in the back-end packaging process. It is designed to pick individual semiconductor dies from a wafer, wafer frame, tray, or other carriers, and accurately place and attach them onto a lead frame, package substrate, ceramic substrate, or module carrier using bonding materials such as epoxy, solder, sinter paste, or eutectic alloys, or through advanced interconnection methods such as flip-chip bonding and thermo-compression bonding. The IC bonder ensures precise alignment, mechanical fixation, thermal conduction, and, in certain packaging structures, electrical interconnection of the die, serving as a critical process step prior to wire bonding, molding, underfill, or module assembly.

In 2025, global sales of C Bonder reached approximately 1,650 units, with an average global market price of around US\$ 562 K/unit. Production capacity varies significantly among manufacturers, with gross profit margins ranging from approximately 30% to 60%.

The IC bonder (die bonder) market represents a mature yet indispensable segment within semiconductor assembly equipment. Its demand is closely tied to global packaging capacity expansion rather than wafer fabrication itself. While conventional leadframe-based packaging still dominates the installed base, incremental demand is increasingly shifting toward advanced packaging. In applications such as AI accelerators, high-performance computing, and advanced memory, die bonding is

evolving from a basic placement process into a precision-critical interconnection step, significantly raising technical requirements.

Growth in this market is driven more by increasing packaging complexity than by unit semiconductor volume alone. Automotive electronics and power semiconductors (SiC/GaN) are pushing demand for high-reliability bonding technologies such as eutectic bonding and silver sintering. At the same time, emerging applications including Micro LED, optoelectronics, and sensors are driving demand for ultra-high precision and high-speed die placement. Furthermore, the rapid adoption of advanced packaging architectures such as chiplets and 3D integration is reinforcing the importance of high-end die bonding equipment, particularly thermo-compression bonding and flip-chip systems.

From a competitive perspective, the market is highly concentrated, dominated by a few leading players primarily based in Japan, Europe, and Hong Kong/China. Core technological barriers lie in motion control, vision alignment, and process integration. Looking ahead, the market is expected to evolve toward platform-based and modular equipment architectures, increasingly integrated with materials and packaging processes. While overall growth remains moderate, structural upgrading driven by advanced packaging will continue to reshape the industry.

This report is a detailed and comprehensive analysis for global IC Bonder market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global IC Bonder market size and forecasts, in consumption value (\$ Million), sales quantity (Unit), and average selling prices (K US\$/Unit), 2021-2032

Global IC Bonder market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Unit), and average selling prices (K US\$/Unit), 2021-2032

Global IC Bonder market size and forecasts, by Type and by Application, in

consumption value (\$ Million), sales quantity (Unit), and average selling prices (K US\$/Unit), 2021-2032

Global IC Bonder market shares of main players, shipments in revenue (\$ Million), sales quantity (Unit), and ASP (K US\$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for IC Bonder

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global IC Bonder market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Besi, ASMPT, Kulicke & Soffa, Panasonic, Kaijo Corporation, Palomar Technologies, Shinkawa, DIAS Automation, Toray Engineering, Fasford Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

IC Bonder market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Fully Automatic

Semi-Automatic

Manual

Market segment by Bonding Mechanism

Epoxy Die Bonder

Eutectic Die Bonder

Solder Die Bonder

Silver Sinter Die Bonder

Flip-Chip Bonder

Thermo-Compression Bonder

Market segment by Throughput

Low-Throughput (10,000 UPH)

Market segment by Application

Conventional IC Packaging

Advanced Packaging

Power Semiconductor Packaging

MEMS and Sensor Packaging

Other

Major players covered

Besi

ASMPT

Kulicke & Soffa

Panasonic

Kaijo Corporation

Palomar Technologies

Shinkawa

DIAS Automation

Toray Engineering

Fasford Technology

West-Bond

Hybond

Mycronic

ITEC Equipment

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe IC Bonder product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of IC Bonder, with price, sales quantity, revenue, and global market share of IC Bonder from 2021 to 2026.

Chapter 3, the IC Bonder competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the IC Bonder breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026. and IC Bonder market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of IC Bonder.

Chapter 14 and 15, to describe IC Bonder sales channel, distributors, customers, research findings and conclusion.

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